

P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY							
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a Q _g (Typ					
- 60	0.058 at V _{GS} = - 10 V	- 6.5	30 nC				
	0.065 at V _{GS} = - 4.5 V	- 5.5	30110				

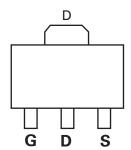
FEATURES

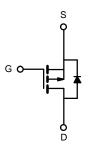
- TrenchFET® Power MOSFET
- 100 % UIS Tested

APPLICATIONS

Load Switch







P-Channel	MOSEFT	ī

ABSOLUTE MAXIMUM RATING	S (T _A = 25 °C, unle	ess otherwise not	ted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 60	V		
Gate-Source Voltage	V _{GS}	± 20	V		
	T _C = 25 °C		- 6.5 ^a		
Continuous Drain Current (T. – 150 °C)	T _C = 70 °C	,	- 5.2		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 4.8 ^b		
	T _A = 70 °C		- 4.1 ^b	A	
Pulsed Drain Current		I _{DM}	- 20		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	- 4.5	7	
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	10.1	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	6.9 ^a	Δ.	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.5 ^b	A	
	T _C = 25 °C		10.4 ^a		
Manianum Danian Dinain ation	T _C = 70 °C	В	6.6 ^a		
Maximum Power Dissipation	T _A = 25 °C	P _D —	2.1 ^b	W	
	T _A = 70 °C		1.1 ^b		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	33	40	°C/W			
Maximum Junction-to-Case	Steady State	R _{thJC}	0.98	1.2	C/VV			

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		68		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	1D = - 200 μΛ		- 5.2		mv/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.2		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Cata Valta na Busin Commant	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 25			А
		V _{GS} = - 10 V, I _D = - 3 A		0.058		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2 A		0.065		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A	20			S
Dynamic ^b			L			
Input Capacitance	C _{iss}			1500		
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		200		pF
Reverse Transfer Capacitance	C _{rss}			150		
Total Octo Observe	Qg	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -5 \text{ A}$		38	56	nC
Total Gate Charge				19	30	
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$		9		
Gate-Drain Charge	Q_{gd}			10		
Gate Resistance	R _g	f = 1 MHz		5.2		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	$V_{DD} = -2 V, R_L = 2 \Omega$		7	15	ns
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -5 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		70	110	
Fall Time	t _f			40	60	
Drain-Source Body Diode Characteristic	s		L	1		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.9	A
Pulse Diode Forward Current ^a	I _{SM}				- 15	
Body Diode Voltage	V_{SD}	I _S = - 3 A		- 1	- 1.5	V
Body Diode Reverse Recovery Time	t _{rr}			45	68	ns
Body Diode Reverse Recovery Charge				59	120	nC
Reverse Recovery Fall Time	t _a	$I_F = -5 \text{ A}, \text{ di/dt} = 10 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		29		ns
Reverse Recovery Rise Time	t _b			16		

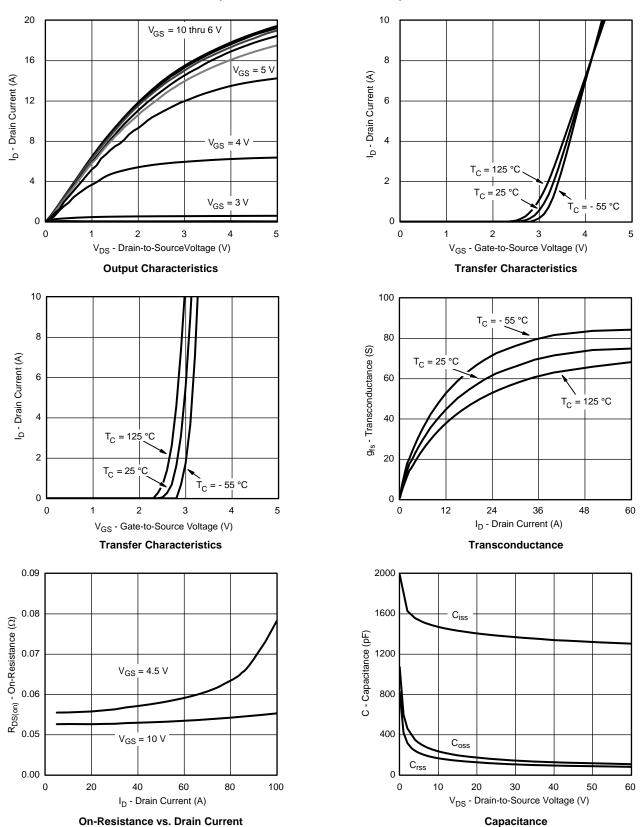
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

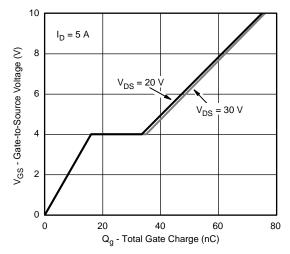


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

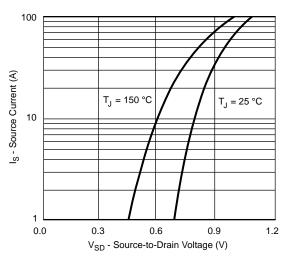




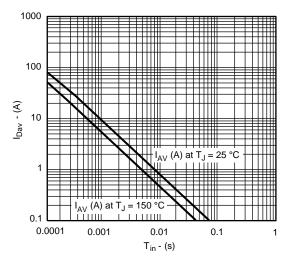
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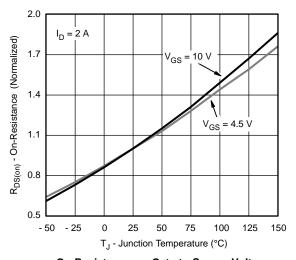
Gate Charge



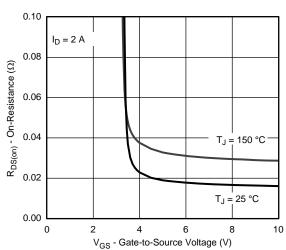
Source-Drain Diode Forward Voltage



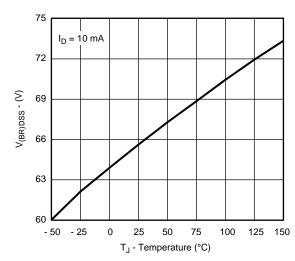
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



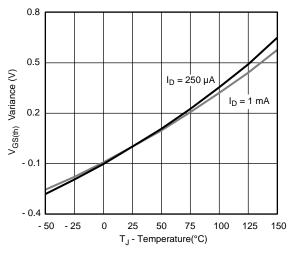
On-Resistance vs. Gate-to-Source Voltage

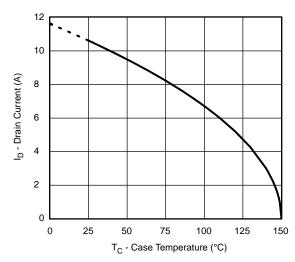


Drain-Source Breakdown Voltage vs. Junction Temperature

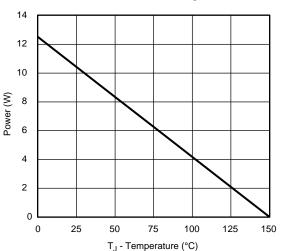


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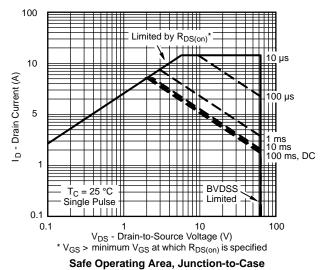




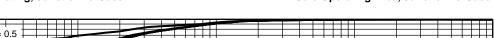
Threshold Voltage

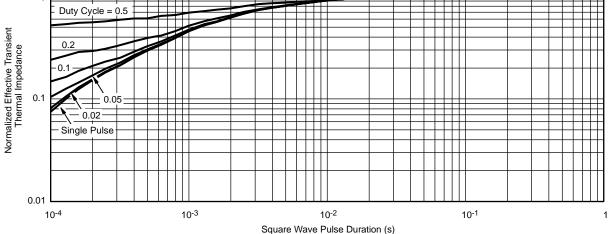


Max. Drain Current vs. Case Temperature



Power Derating, Junction-to-Case

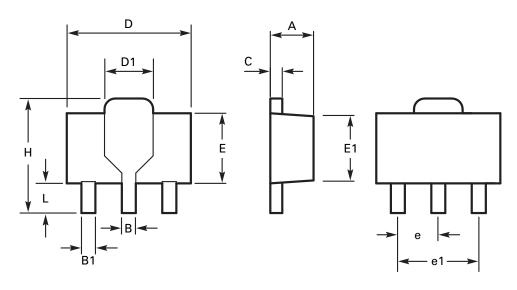




Normalized Thermal Transient Impedance, Junction-to-Case



Package outline - SOT89



DIM	Millin	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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